1. Pitch Adapter to Chip Bonds

**Lead Reference System (L): Pitch Adapter**
- Operator point 1: 1 pad, bottom left corner
- Operator point 2: 63 pad, bottom right corner

**Die Reference System (U): Chip**
- Operator point 1: 1 pad, top left corner
- Operator point 2: 63 pad, top right corner

**First Bond: Pitch Adapter**
- Bond time: 20 ms
- USG Current: 60 mA
- Force: 28
- Tip: 20 mils

**Second Bond: Chip**
- Bond time: 25 ms
- USG Current: 50 mA
- Force: 35
- Tip: 20 mils

**Loop Parameters:**
- Shape: square
- Loop height: short bonds 33 mils, long bonds 48 mils
- Clear height: short bonds 100 mils, long bonds 100 mils
- Clamp close at loop

**Tail Parameters:**
- Feed: 75
## 2. Hybrid Bias Bonds

**Bias Bonds Location:**

![Diagram of bias bonds location]

**Pitch Adapter to Gold Pad on Hybrid:**

Place 4 bonds, 2 short, 2 long

![Diagram of bond placement]

<table>
<thead>
<tr>
<th><strong>First Bond: Pitch Adapter</strong></th>
<th><strong>Second Bond: Gold</strong></th>
</tr>
</thead>
<tbody>
<tr>
<td>Bond time: 20ms</td>
<td>Bond time: 35 ms</td>
</tr>
<tr>
<td>USG Current: 60 mA</td>
<td>USG Current: 65 mA</td>
</tr>
<tr>
<td>Force: 28</td>
<td>Force: 25</td>
</tr>
<tr>
<td>Tip: 20 mils</td>
<td>Tip: 20 mils</td>
</tr>
</tbody>
</table>

**Loop Parameters:**

- Shape: square
- Loop height: short bonds 60 mils, longs bonds 70 mils
- Clamp close at loop

**Tail Parameters:**

- Feed: 75